



Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
-100V	42mΩ@-10V	-30A
	48mΩ@-4.5V	

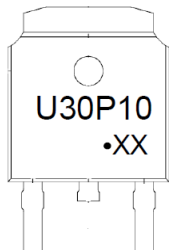
Feature

- Super high dense cell design
- Advanced trench process technology
- Reliable and rugged
- High density cell design for ultra low On-Resistance

Application

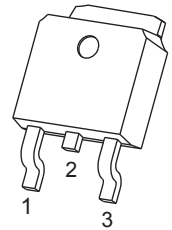
- Portable equipment and battery powered systems

MARKING:



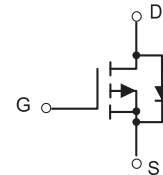
U30P10 = Device Code
XX = Date Code
Solid Dot = Green Indicator

TO-252-2L



1. GATE
2. DRAIN
3. SOURCE

Schematic diagram



ABSOLUTE MAXIMUM RATINGS ($T_C=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	I_D	-30	A
Pulsed Drain Current ²	I_{DM}	-150	A
Single Pulse Avalanche Energy ³	E_{AS}	345	mJ
Avalanche Current ³	I_{AS}	28	A
Total Power Dissipation ⁵	P_D	120	W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	1.25	$^\circ\text{C/W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~ +150	$^\circ\text{C}$

MOSFET ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-100			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -80V, V _{GS} = 0V			-1	μA
Gate - Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
On Characteristics⁴						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-1.5	-2.0	-2.5	V
Drain-source On-resistance	R _{DS(on)}	V _{GS} = -10V, I _D = -15A		42	55	mΩ
		V _{GS} = -4.5V, I _D = -15A		48	65	
Forward transconductance	g _{FS}	V _{DS} = -10V, I _D = -10A	20			S
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = -25V, V _{GS} = 0V, f = 1MHz		6616		pF
Output Capacitance	C _{oss}			230		
Reverse Transfer Capacitance	C _{rss}			130		
Switching Characteristics						
Total Gate Charge	Q _g	V _{DS} = -80V, V _{GS} = -10V, I _D = -14A		95		nC
Gate-source Charge	Q _{gs}			19		
Gate-drain Charge	Q _{gd}			15		
Turn-on Delay Time	t _{d(on)}	V _{DD} = -50V, V _{GS} = -10V, I _D = -14A, R _G = 3.3Ω		23		ns
Turn-on Rise Time	t _r			34		
Turn-off Delay Time	t _{d(off)}			125		
Turn-off Fall Time	t _f			65		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V _{SD}	V _{GS} = 0V, I _S = -10A			-1.2	V
Continuous Source Current	I _S	V _G = V _D = 0V, Force Current			-30	A
Reverse Recovery Time	t _{rr}	I _F = -14A, dI/dt = 100A/μs		31.2		nS
Reverse Recovery Charge	Q _{rr}				31.97	

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width ≤ 10μs, duty cycle ≤ 1%.
- 3.E_{AS} condition: V_{DD} = 34V, V_{GS} = 10V, L = 0.5mH, R_G = 25Ω Starting T_J = 25°C.
- 4.Pulse Test : Pulse Width ≤ 300μs, duty cycle ≤ 2%.
- 5.The power dissipation P_D is limited by T_{J(MAX)} = 150°C.And device mounted on a large heatsink
- 6.Device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C.

Typical Electrical and Thermal Characteristics

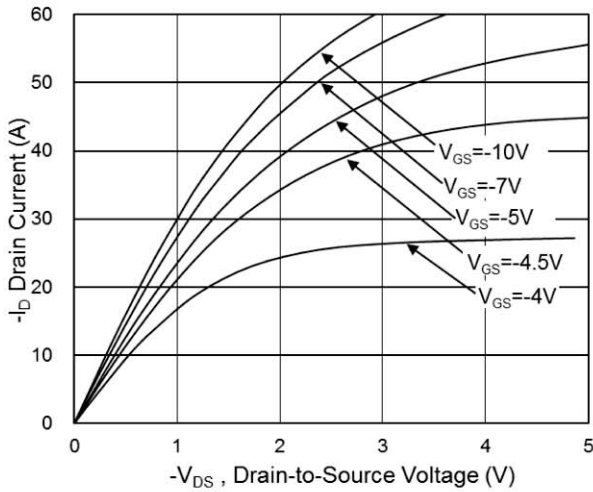


Fig.1 Typical Output Characteristics

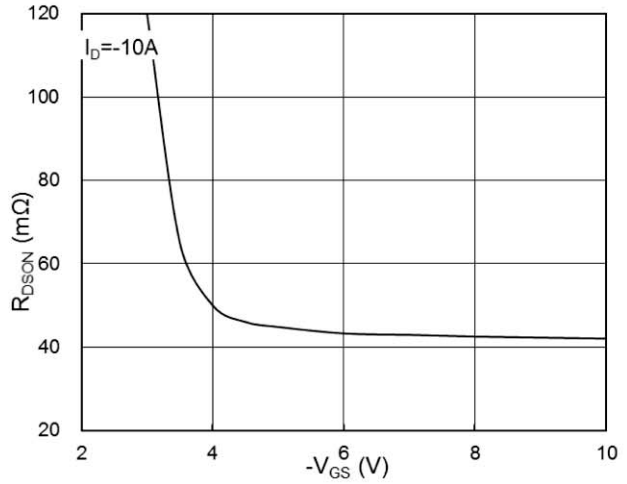


Fig.2 On-Resistance vs. G-S Voltage

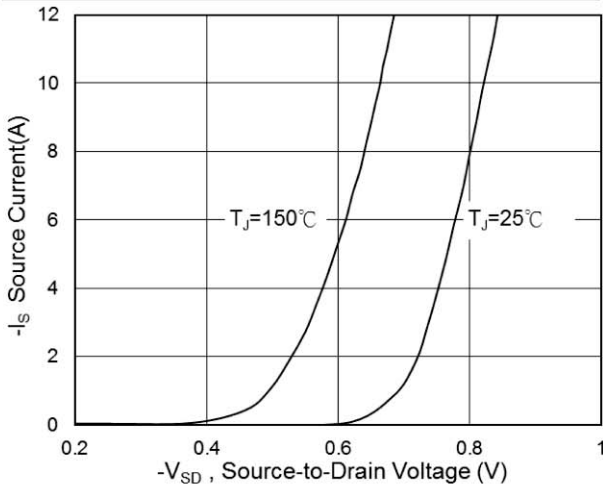


Fig.3 Typical S-D Diode Forward Voltage

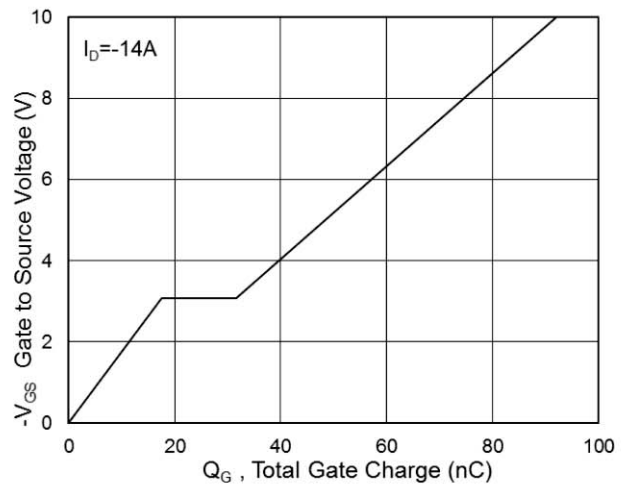


Fig.4 Gate-Charge Characteristics

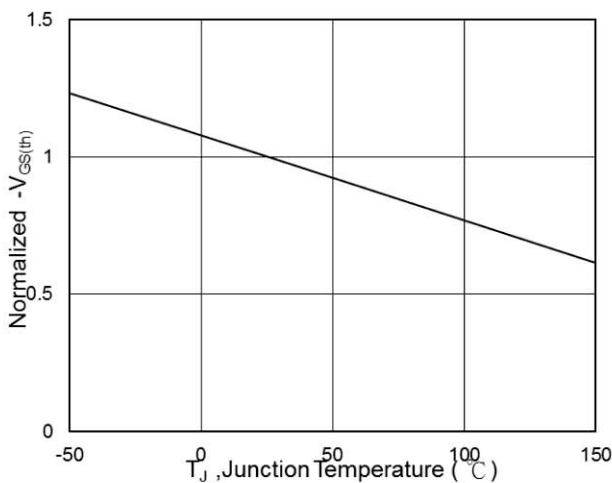


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

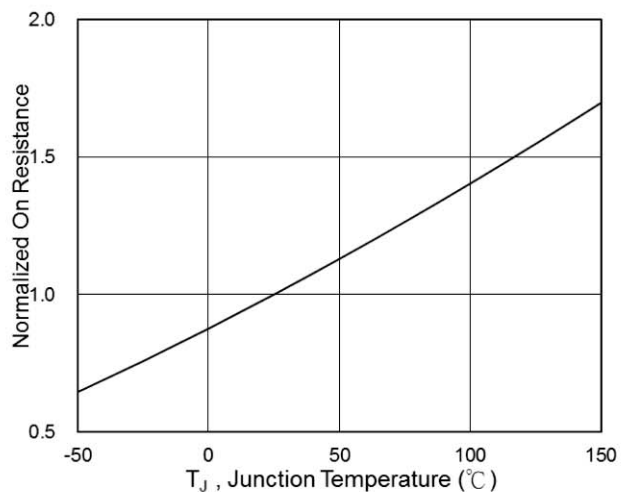


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

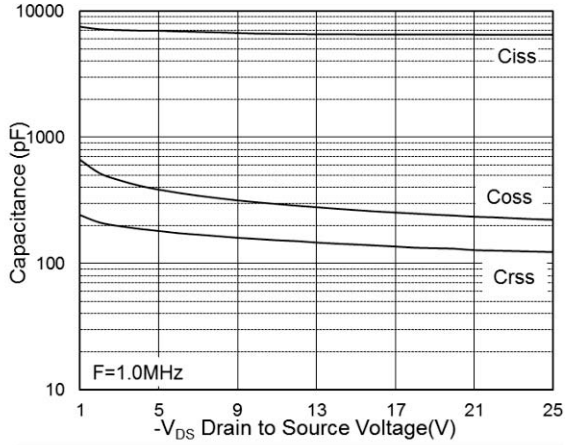


Fig.7 Capacitance

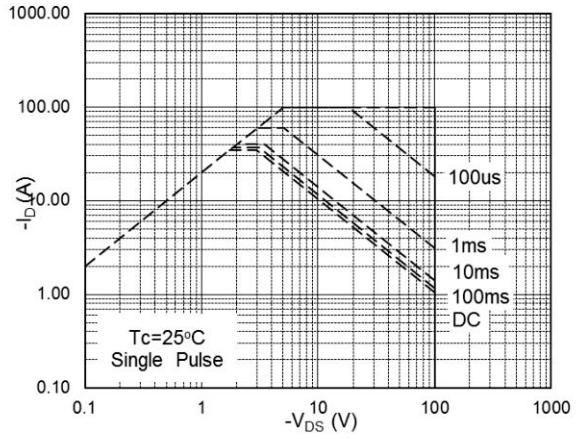


Fig.8 Safe Operating Area

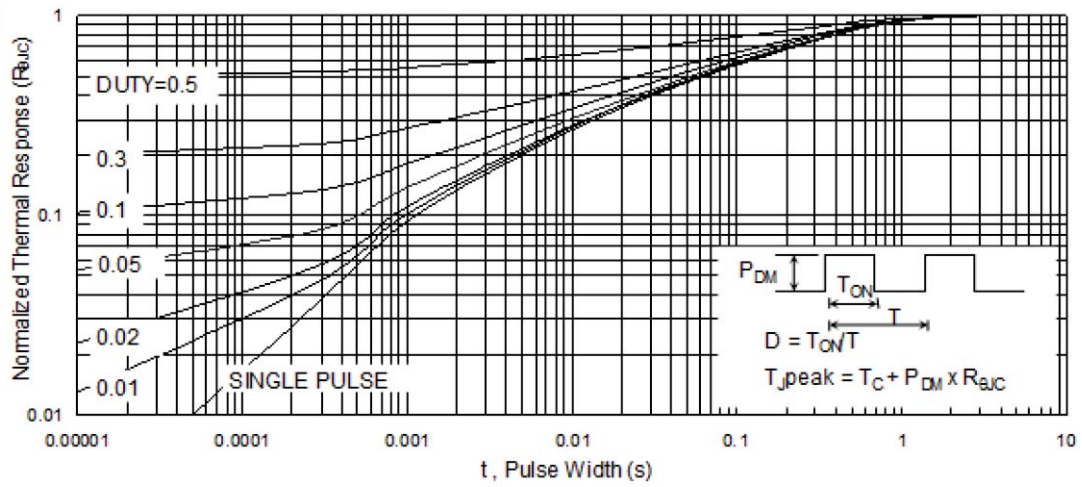
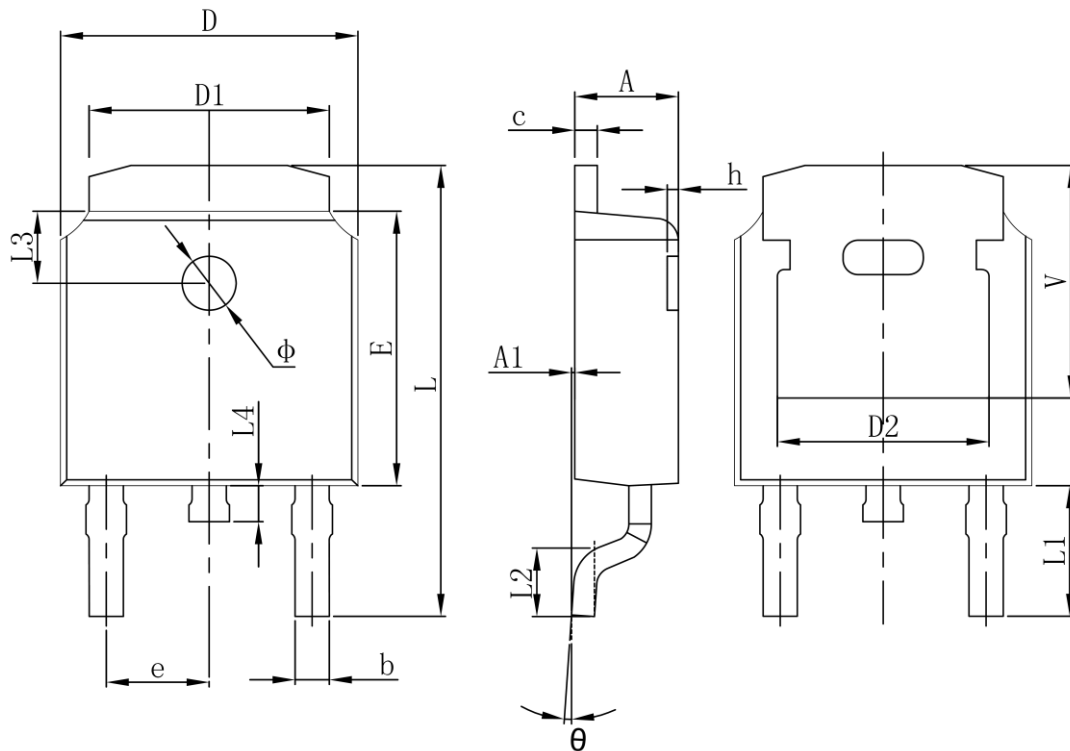


Fig.9 Normalized Maximum Transient Thermal Impedance

TO-252-2L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.635	0.770	0.025	0.030
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830REF		0.190REF	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.712	10.312	0.382	0.406
L1	2.900REF		0.114REF	
L2	1.400	1.700	0.055	0.067
L3	1.600REF		0.063REF	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.250REF		0.207REF	

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